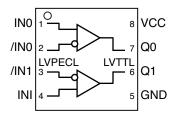
PACKAGE/ORDERING INFORMATION



8-Pin MLF®
Ultra-Small Outline (2mm x 2mm)

Ordering Information

| Part Number | Package Type | Operating Range | Package Marking | Lead Finish |
|-----------------------------|-----------------|--------------------|--|-------------------|
| SY89323LMITR | MLF-8 | Industrial | 323 | Sn-Pb |
| SY89323LMGTR ⁽¹⁾ | MLF-8 | Industrial | 323 with Pb-Free bar-line indicator | Pb-Free NiPdAu |

Note:

1. Pb-Free package is recommended for new designs.

PIN DESCRIPTION

| Pin Number | Pin Name | Туре | Pin Function |
|------------|---------------------|--------------|---|
| 1, 4 | INO, IN1 | ECL Input | Differential PECL/ECL Input: Internal $75k\Omega$ pull-down resistor. If left open, pin defaults LOW. Q output will be LOW. See "Input Interface Applications" section for single-ended inputs. |
| 2, 3 | /IN0, /IN1 | ECL Input | Differential PECL/ECL Input: Internal $75k\Omega$ pull-up and pull-down resistors. If left floating, pin defaults to $V_{CC}/2$. When not used, this input can be left open. See "Input Interface Applications" section for single-ended inputs. |
| 7, 6 | Q0, Q1 | LVTTL Output | Single-ended LVTTL Outputs: Default to LOW if IN inputs left open. |
| 8 | VCC | VCC Power | Positive Power Supply: Bypass with 0.1μF//0.01μF low ESR capacitors. |
| 5 | GND, Exposed Pad | Ground | GND and exposed pad must be tied to ground plane. |

Absolute Maximum Ratings(1)

| Supply Voltage (V _{CC}) | 0.5V to +3.8V |
|---|-------------------------|
| Input Voltage (V _{IN}) | 0.5V to V _{CC} |
| LVPECL Output Current (I _{OUT}) | |
| Continuous | 50mA |
| Surge | 100mA |
| Input Current | |
| Source or sink current on IN, /IN | ±50mA |
| Lead Temperature (soldering, 20 sec.) | +260°C |
| Storage Temperature (T _S) | –65°C to +150°C |

Operating Ratings⁽²⁾

| Supply Voltage (V _{CC}) | 3.0V to 3.6V |
|---|---------------|
| Ambient Temperature (T _A) | 40°C to +85°C |
| Package Thermal Resistance, Note 3 | |
| $MLF^{	ext{B}}$ (θ_{JA}) Still-Air | |
| Still-Air | 93°C/W |
| 500lfpm | |
| $MLF^{	ext{@}}\left(\Psi_{JB}\right)$ | |
| Junction-to-Board | 60°C/W |

LVTTL DC ELECTRICAL CHARACTERISTICS

 $T_{\Delta} = -40^{\circ}$ C to +85°C, unless otherwise noted.

| Symbol | Parameter | Condition | Min | Тур | Max | Units |
|-----------------|------------------------------|--------------------------|-----|-----|------|-------|
| V _{OH} | Output HIGH Voltage | I _{OH} = -3.0mA | 2.0 | _ | _ | V |
| V _{OL} | Output LOW Voltage | $I_{OL} = 24mA$ | _ | _ | 0.5 | V |
| I _{CC} | Power Supply Current | | _ | _ | 30 | mA |
| I _{os} | Output Short Circuit Current | V _{OUT} = 0V | -80 | _ | -240 | mA |

LVPECL DC ELECTRICAL CHARACTERISTICS

 V_{CC} = +3.3V±10%; T_A = -40°C to +85°C, unless otherwise noted.

| Symbol | Parameter | Condition | Min | Тур | Max | Units |
|--------------------|------------------------------|-----------|------------------------|-----|------------------------|-------|
| V_{IH} | Input HIGH Voltage | | V _{CC} -1.230 | _ | V _{CC} -0.735 | V |
| V _{IL} | Input LOW Voltage | | V _{CC} -1.950 | _ | V _{CC} -1.475 | V |
| V _{IHCMR} | Input HIGH Common Mode Range | Note 4 | V _{EE} +1.5 | - | V _{CC} | V |
| V_{PP} | Minimum Peak-to-Peak Input | | 200 | | | mV |
| I _{IH} | Input HIGH Current | | _ | _ | 150 | μΑ |
| I _{IL} | Input LOW Current IN | | 0.5 | _ | _ | μА |
| | /IN | | -300 | _ | _ | μΑ |

Notes:

- 1. Permanent device damage may occur if absolute maximum ratings are exceeded. This is a stress rating only and functional operation is not implied at conditions other than those detailed in the operational sections of this data sheet. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.
- 2. The data sheet limits are not guaranteed if the device is operated beyond the operating ratings.
- 3. Package thermal resistance assumes exposed pad is soldered (or equivalent) to the devices most negative potential on the PCB.
- 4. V_{IHCMR} (min) varies 1:1 with V_{EE} , max varies 1:1 with V_{CC} .

AC ELECTRICAL CHARACTERISTICS

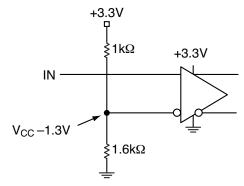
 $V_{CC} = +3.3V \pm 10\%$; $C_L = 20 pF$, $T_A = -40 ^{\circ}C$ to $+85 ^{\circ}C$, unless otherwise noted. All parameters guaranteed by design and characterization.

| Symbol | Parameter | Condition | Min | Тур | Max | Units |
|----------------------------------|---------------------------------------|------------|-----|-----|-----|-------------------|
| f _{MAX} | Maximum Input Frequency | Notes 1, 2 | 275 | _ | _ | MHz |
| t _{pd} | Propagation Delay | | 1.5 | _ | 2.5 | ns |
| t _{skpp} | Part-to-Part Skew | Notes 3 | _ | _ | 0.5 | ns |
| t _{skew++} | Within-Device Skew | Notes 4 | _ | _ | 0.3 | ns |
| t _{skew} | Within-Device Skew | Notes 5 | _ | _ | 0.3 | ns |
| t _{jitter} | Cycle-to-Cycle | Note 6 | | | 2 | ps _{RMS} |
| | Total Jitter | Note 7 | | | 25 | ps _{PP} |
| t _r t _f | Output Rise/Fall Time 1.0V to 2.0V | | 0.5 | _ | 1.0 | ns |

Notes:

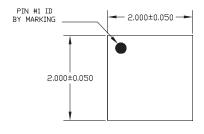
- 1. Frequency at which guaranteed for functionality. V_{OH} and V_{OL} levels are guaranteed at DC only.
- 2. The f_{MAX} value is specified as the minimum guaranteed maximum frequency. Actual operational maximum frequency may be greater.
- 3. Device-to-Device Skew considering HIGH-to-HIGH transitions at common V_{CC} level.
- 4. Within-Device Skew considering HIGH-to -HIGH transitions at common V_{CC} level.
- 5. Within-Device Skew considering LOW-to-LOW transitions at common V_{CC} level.
- Cycle-to-cycle jitter definition: The variation of periods between adjacent cycles, T_n T_{n-1}, where T is the time between rising edges of the output signal.
- Total jitter definition: with an ideal clock input of frequency ≤ f_{MAX}, no more than one output edge in 10¹² output edge will deviate by more than the specified peak-to-peak jitter value.

INPUT INTERFACE APPLICATIONS

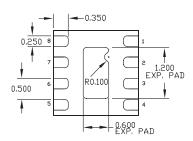


Single-Ended Input (Terminating unused input)

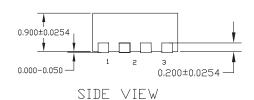
8-PIN ULTRA-SMALL EPAD-MicroLeadFrame® (MLF-8)



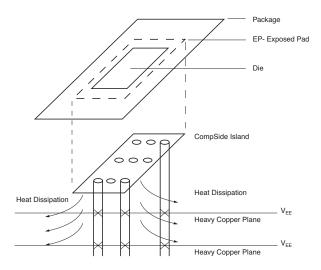
TOP VIEW



BOTTOM VIEW



ALL DIMENSIONS ARE IN MILLIMETERS.
MAX. PACKAGE WARPAGE IS 0.05 mm.
MAXIMM ALLOWABE BURRS IS 0.076 mm IN ALL DIRECTIONS.
PIN #1 ID ON TOP WILL BE LASER/INK MARKED.



PCB Thermal Consideration for 8-Pin MLF® Package

Package Notes:

- 1. Package meets Level 2 qualification.
- 2. All parts are dry-packaged before shipment.
- 3. Exposed pads must be soldered to a ground for proper thermal management.

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